

**ABSTRACT OF DISCLOSURE**

A transparent base having a GaN semiconductor light-emitting device fixed thereon with a transparent adhesive is fitted to lead frames by flip chip bonding in such a manner that the light from the device is emitted outside through the substrate of the device, the adhesive, the base, and a sealing resin in this order. The apparatus has high reliability because the sealing resin in the dominant direction of light emission is protected against color change due to the heat generated from the device.

[illegible]